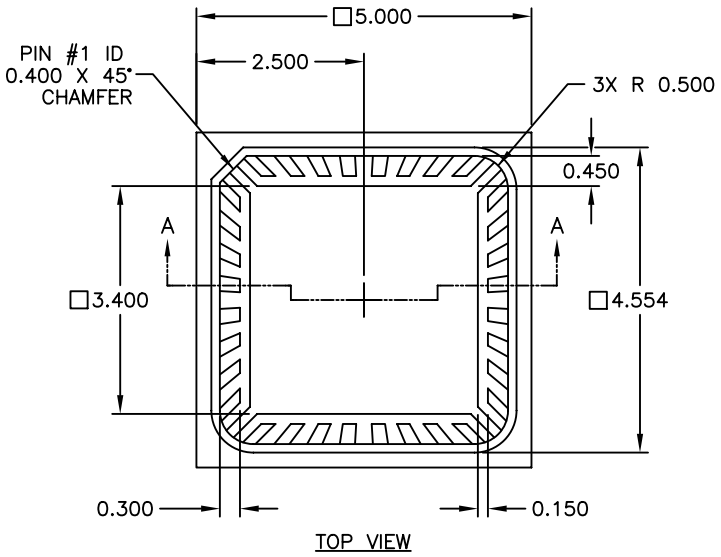
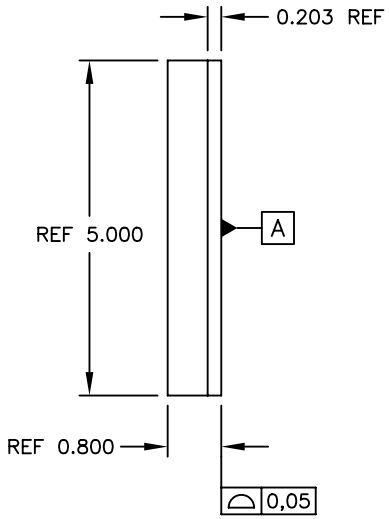
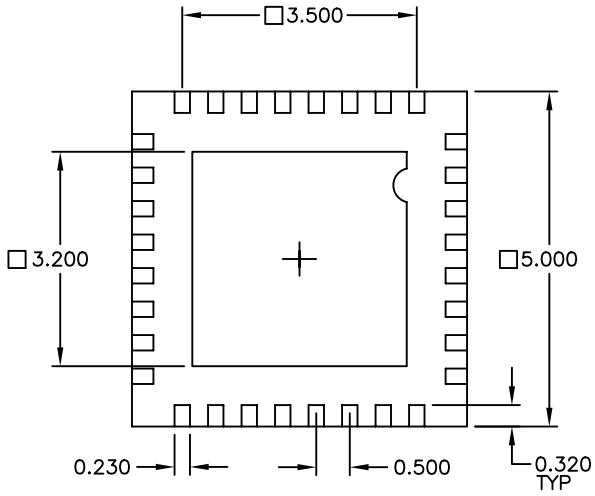
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	

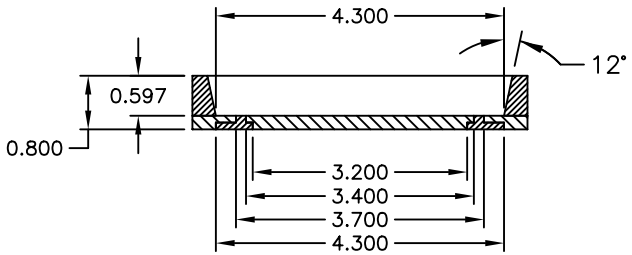


TOP VIEW





BOTTOM VIEW



SECTION A–A

NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK–PAK FOR DETAILS.
2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL–C–26074, CLASS 1,
   100 TO 300 MICROINCHES (2.5um – 7.6um) THICK.
   GOLD PLATE PER MIL–G–45204, TYPE 3, GRADE A, CLASS 1
   (40 TO 80 MICROINCHES (1um – 2um) THICK).
   BODY SURFACE FINISH: VDI 21–24 (1.12–1.6 Ra).
3. PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO–220.

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETER
TOLERANCES ARE:
X.XX ± 0.15 X.XXXX ±---
X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	CAD DEPT.	DATE 3/18/10
APP BY	STEVE S.	DATE 3/18/10
CUSTOMER	---	

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QUIK-PAK
www.icproto.com
10987 VIA FRONTERA
SAN DIEGO, CA. 92127
PHONE: (858) 674-4676 FAX: (858) 674-4681

5mm X 5mm
QFN 32 LEAD 0mPP

SIZE	PART NO.	REV
A	QP–QFN32–5MM–.5MM	A2

SCALE NONE | CAD FILE | SHEET 1 OF 1